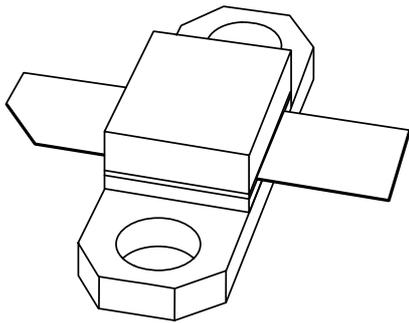


# DATA SHEET



## **BLL1214-35** L-band radar LDMOS driver transistor

Product specification

2002 Sep 27

# L-band radar LDMOS driver transistor

# BLL1214-35

## FEATURES

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- High power gain
- Easy power control
- Excellent ruggedness
- Source on mounting base eliminates DC isolators, reducing common mode inductance.

## APPLICATIONS

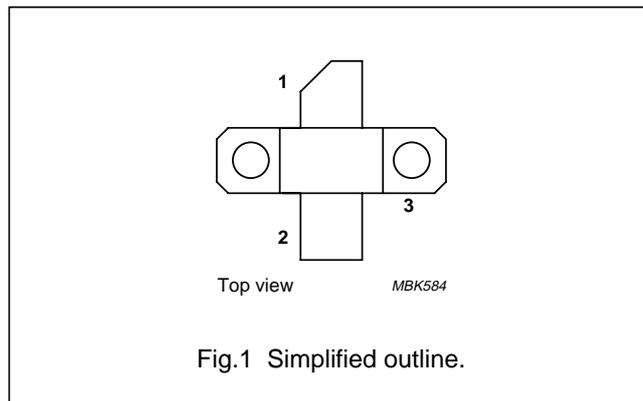
- L-band radar applications in the 1200 to 1400 MHz frequency range.

## DESCRIPTION

Silicon N-channel enhancement mode lateral D-MOS transistor encapsulated in a 2-lead flange package (SOT467C) with a ceramic cap. The common source is connected to the flange.

## PINNING - SOT467C

PIN	DESCRIPTION
1	drain
2	gate
3	source, connected to flange



## QUICK REFERENCE DATA

RF performance at  $T_h = 25\text{ °C}$  in a common source test circuit.

MODE OF OPERATION	f (MHz)	$V_{DS}$ (V)	$P_L$ (W)	$G_p$ (dB)	$\eta_D$ (%)
Pulsed class-AB; $t = 1\text{ ms}$ ; $\delta = 10\%$	1200 to 1400	36	35	>13	>43

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{DS}$	drain-source voltage		–	75	V
$V_{GS}$	gate-source voltage		–	$\pm 15$	V
$P_{tot}$	total power dissipation	under RF conditions; $T_h \leq 25\text{ °C}$	–	110	W
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–	200	°C

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## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$Z_{th\ j-h}$	thermal impedance from junction to heatsink	$T_h = 25\text{ °C}$ ; note 1	1.1	K/W

## Note

1. Thermal resistance is determined under RF operating conditions;  $t_p = 1\text{ ms}$ ,  $\delta = 10\%$ .

## CHARACTERISTICS

$T_j = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0$ ; $I_D = 0.7\text{ mA}$	75	–	–	V
$V_{GSth}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}$ ; $I_D = 70\text{ mA}$	4.5	–	5.5	V
$I_{DSS}$	drain-source leakage current	$V_{GS} = 0$ ; $V_{DS} = 36\text{ V}$	–	–	10	$\mu\text{A}$
$I_{DSX}$	on-state drain current	$V_{GS} = V_{GSth} + 9\text{ V}$ ; $V_{DS} = 10\text{ V}$	10	–	–	A
$I_{GSS}$	gate leakage current	$V_{GS} = \pm 20\text{ V}$ ; $V_{DS} = 0$	–	–	125	nA
$g_{fs}$	forward transconductance	$V_{DS} = 10\text{ V}$ ; $I_D = 2.5\text{ A}$	–	2	–	S
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$ ; $I_D = 2.5\text{ A}$	–	300	–	$\text{m}\Omega$

## APPLICATION INFORMATION

RF performance in a common source class-AB circuit.  $T_h = 25\text{ °C}$ ;  $Z_{th\ mb-h} = 0.65\text{ K/W}$ , unless otherwise specified.

MODE OF OPERATION	f (MHz)	$V_{DS}$ (V)	$I_{DQ}$ (mA)	$P_L$ (W)	$G_p$ (dB)	$\eta_D$ (%)
Pulsed class-AB; $t = 1\text{ ms}$ ; $\delta = 10\%$	1200 to 1400	36	50	35	>13	>43

## Ruggedness in class-AB operation

The BLL1214-35 is capable of withstanding a load mismatch corresponding to  $V_{SWR} = 5 : 1$  through all phases under the following conditions:  $V_{DS} = 36\text{ V}$ ; frequency from 1200 MHz to 1400 MHz at rated load power.

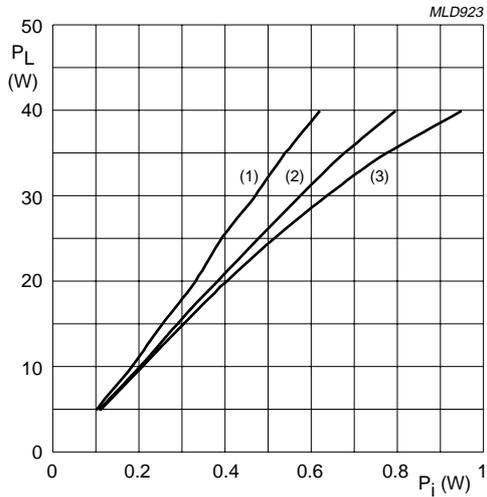
## Typical impedance

FREQUENCY (GHZ)	$Z_s$ ( $\Omega$ )	$Z_L$ ( $\Omega$ )
1.20	$6.48 - j\ 3.9$	$1.95 + j\ 3.27$
1.25	$3.88 - j\ 3.2$	$1.90 + j\ 2.57$
1.30	$3.28 - j\ 2.4$	$2.01 + j\ 2.27$
1.35	$2.55 - j\ 1.48$	$2.20 + j\ 2.26$
1.40	$1.69 - j\ 0.51$	$1.72 + j\ 2.35$

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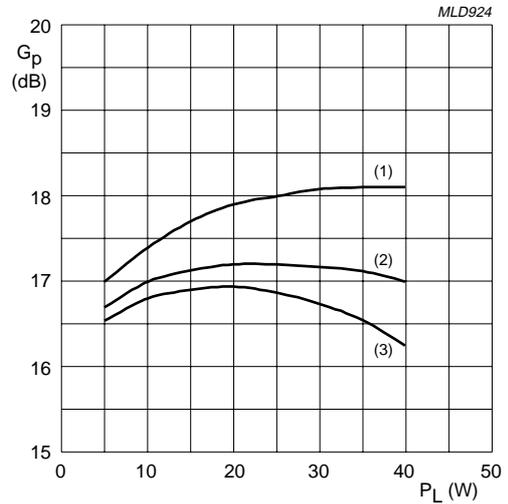
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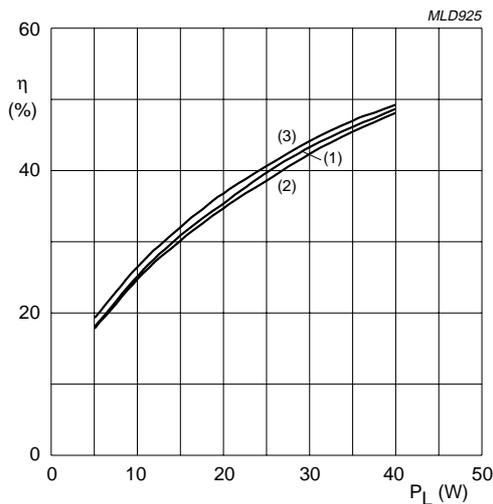
(1)  $f = 1.2$  GHz. (2)  $f = 1.3$  GHz. (3)  $f = 1.4$  GHz.  
 $t_p = 1$  ms;  $\delta = 10\%$ .

Fig.2 Load power as a function of input power; typical values.



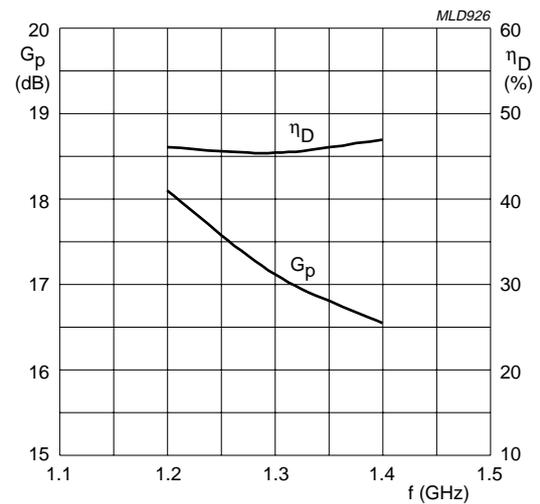
(1)  $f = 1.2$  GHz. (2)  $f = 1.3$  GHz. (3)  $f = 1.4$  GHz.  
 $t_p = 1$  ms;  $\delta = 10\%$ .

Fig.3 Power gain as a function of load power; typical values.



(1)  $f = 1.2$  GHz. (2)  $f = 1.3$  GHz. (3)  $f = 1.4$  GHz.  
 $t_p = 1$  ms;  $\delta = 10\%$ .

Fig.4 Efficiency as a function of load power; typical values.



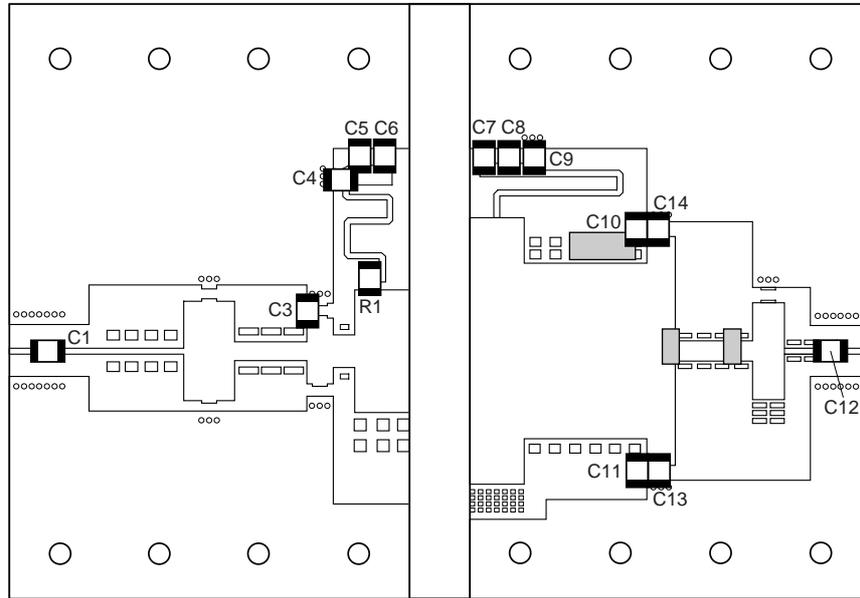
$t_p = 1$  ms;  $\delta = 10\%$ .

Fig.5 Power gain and efficiency as functions of frequency; typical values.

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MCE033

Shaded areas indicate tuning stubs.

Fig.6 Component layout.

List of components (see Fig.6)

COMPONENT	DESCRIPTION	VALUE	CATALOGUE NO.
C1, C12	capacitor	51 pF	ATC100A
C3	capacitor	6.8 pF	ATC100A
C4, C9	capacitor	47 pF	ATC100A
C6, C7	capacitor	4.7 $\mu$ F/50 V	475 50k 952
C5, C8	capacitor	2.3 nF	ATC100B
C10	capacitor	2.7 pF	ATC100A
C11	capacitor	1.0 pF	ATC100A
C13, C14	capacitor	1.5 pF	ATC100A
R1	chip resistor	82 $\Omega$	

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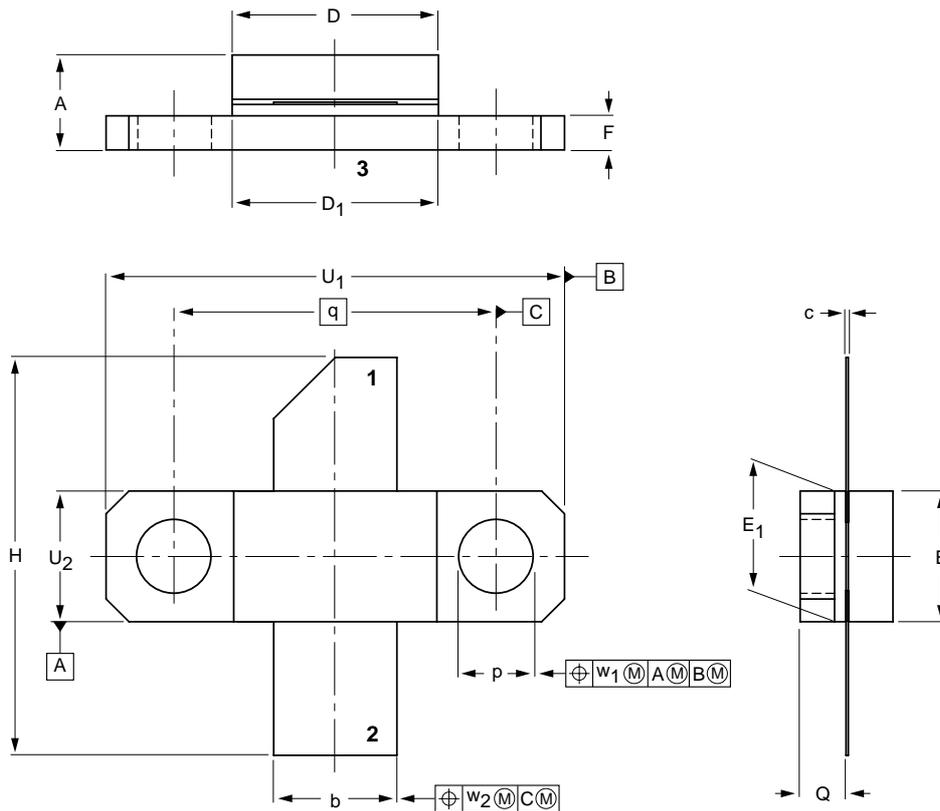
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PACKAGE OUTLINE

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Flanged LDMOST ceramic package; 2 mounting holes; 2 leads

SOT467C



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A	b	c	D	D <sub>1</sub>	E	E <sub>1</sub>	F	H	p	Q	q	U <sub>1</sub>	U <sub>2</sub>	w <sub>1</sub>	w <sub>2</sub>
mm	4.67 3.94	5.59 5.33	0.15 0.10	9.25 9.04	9.27 9.02	5.92 5.77	5.97 5.72	1.65 1.40	18.54 17.02	3.43 3.18	2.21 1.96	14.27	20.45 20.19	5.97 5.72	0.25	0.51
inch	0.184 0.155	0.220 0.210	0.006 0.004	0.364 0.356	0.365 0.355	0.233 0.227	0.235 0.225	0.065 0.055	0.73 0.67	0.135 0.125	0.087 0.077	0.562	0.805 0.795	0.235 0.225	0.010	0.020

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT467C						99-12-06 99-12-28

## L-band radar LDMOS driver transistor

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For additional information please visit <http://www.semiconductors.philips.com>. Fax: +31 40 27 24825

For sales offices addresses send e-mail to: [sales.addresses@www.semiconductors.philips.com](mailto:sales.addresses@www.semiconductors.philips.com).

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